

Product Change Notification / ASER-10MDZB313

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12-Jul-2023

Product Category:

Crypto Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5370 Final Notice: Qualification of S703LS as an additional die attach material for selected AT88S and AT88A device families available in SCC (12.6x11.4x0.58mm) package.

Affected CPNs:

ASER-10MDZB313_Affected_CPN_07122023.pdf ASER-10MDZB313_Affected_CPN_07122023.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of S703LS as an additional die attach material for selected AT88S and AT88A device families available in SCC (12.6x11.4x0.58mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change						
Assembly Site	AIC Semiconductor	AIC Semiconductor	AIC Semiconductor					

	Sdn Bhd	Sdn Bhd	Sdn Bhd		
	(AIC)	(AIC)	(AIC)		
Wire Material	Au	Au	Au		
Die Attach Material	2035SC	2035SC	S703LS		
Molding Compound Material	1650	1650	1650		
Lead-Frame Material	Epoxy Glass Film base	Epoxy Glass Film base	Epoxy Glass Film base		
Leau-Franie Material	with Copper	with Copper	with Copper		

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve on time delivery performance by qualifying S703LS as an additional die attach material.

Change Implementation Status:In Progress

Estimated First Ship Date: August 30, 2023 (date code: 2335)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	December 2022		>	July 2023			August 2023									
Workweek	4 9	5 0	5 1	5 2	5 3		2 6	2 7	2 8	2 9	3 0	3 1	3 2	3	3 4	3 5
Initial PCN Issue Date			Χ													
Qual Report Availability									Χ							
Final PCN Issue Date									Χ							
Estimated Implementation Date																Х

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:December 09, 2022: Issued initial notification.

March 16, 2023: Re-issued initial notification to update the Die attach material from \$703LT to \$703LS. Update the timetable summary to reflect new qualification date from December 2022 to April 2023.

July 13, 2023: Issued final notification. Attached Qual Report. Added the estimated qualification report on August 30, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN ASER-10MDZB313 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

AT88SC1003-09JT-02

AT88SC1003-09ET-01

AT88SC1003-09ET-00

AT88SC0104C-MPTG

AT88SC0204C-MPTG

AT88SC0404C-MPTG

AT88SC0808C-MPTG

AT88SC1616C-MPTG

AT88SC0104C-MP

AT88SC0204C-MP

AT88SC0404C-MP

AT88SC0808C-MP

AT88SC1616C-MP

AT88SC0104C-MJTG

AT88AA001-MJ

AT88AA001-MJTG

AT88SC0204C-MJTG

AT88SC0404C-MJTG

AT88SC0808C-MJTG

AT88AK001-MJ

AT88SC1616C-MJTG

AT88SC0104C-MJ

AT88SC0204C-MJ

AT88SC0404C-MJ

AT88SC0808C-MJ

AT88SC1616C-MJ

AT88SC0104C-ME

AT88SC0204C-ME

AT88SC0404C-ME

AT88SC0808C-ME

AT88SC1616C-ME

AT88SC102-09PT-01

AT88SC102-09ET-17

AT88SC102-09ET-19

AT88SC102-09ET-01

AT88SC102-09ET-03

AT88SC102-09ET-08

AT88SC102-09ET-00

AT88SC1604A-09PT-66

AT88SC153-09PT-00

AT88SC153-09PT-01

AT88SC153-09ET-00

AT88SC1608-09PT-07

AT88SC1608-09PT-01

AT88SC1608-09ET-10

AT88SC1608-09ET-00

Date: Wednesday, July 12, 2023

ASER-10MDZB313 - CCB 5370 Final Notice: Qualification of S703LS as an additional die attach material for selected AT88S and AT88A device families available in SCC (12.6x11.4x0.58mm) package. AT88SC3216C-MJTG AT88SC6416C-MJTG AT88SC12816C-MJTG AT88SC25616C-MJTG AT88SC3216C-MJ AT88SC6416C-MJ AT88SC12816C-MJ AT88SC25616C-MJ AT88SC25616C-MB AT88SC0104CA-MPTG AT88SC0204CA-MPTG AT88SC0404CA-MPTG AT88SC0808CA-MPTG AT88SC0104CA-MP AT88SC0204CA-MP AT88SC0404CA-MP AT88SC0808CA-MP AT88SC0104CA-MJTG AT88SC0204CA-MJTG AT88SC0404CA-MJTG

AT88SC0808CA-MJTG

AT88SC0104CA-MJ

AT88SC0204CA-MJ

AT88SC0404CA-MJ

AT88SC0808CA-MJ